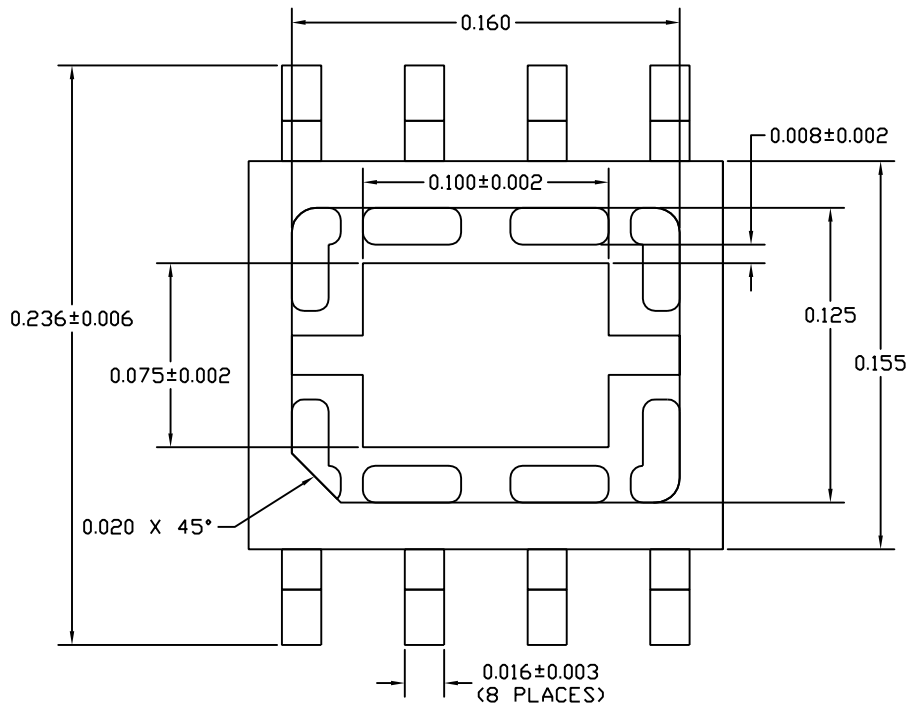
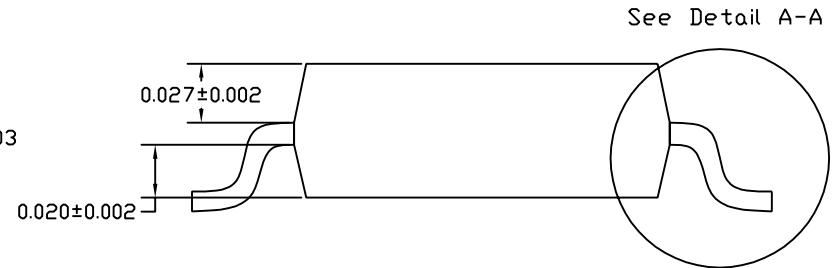
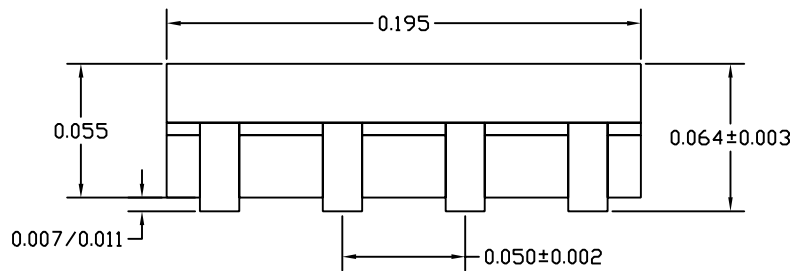
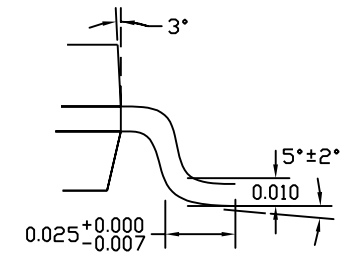


ECN	REV.	DESCRIPTION	DATE	APP'D:
10008	-	INITIAL RELEASE	01/22/01	BF



DETAIL A-A



NOTES:
 BODY : PLASTIC, SEMICONDUCTOR GRADE
 LEAD FRAME : COPPER, OLIN 194
 LEAD FINISH : 50µIN Au, OVER 50µIN NI
 FRAME THICKNESS : 0.008" +/- 0.001"



TITLE: 8 Lead SOIC Open-Pak (0.150" Wide)		
MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: S.D.
GEN. TOL.: ±0.05	DATE: 10/29/00	APP'D: BF 01/22/01
SSM P/N: PS0081501	DWG. NO.: SOIC08-OP-01	REV.: -